



SRAM MODULE 768KBit (32K x 24-Bit)
Part No. HMS3224M3, HMS3224Z3

GENERAL DESCRIPTION

The HMS3224M3/Z3 is a high-speed static random access memory (SRAM) module containing 32,768 words organized in a x24-bit configuration. The module consists of three 32K x 8 SRAMs mounted on a 56-pin, single-sided, FR4-printed circuit board.

Writing to the device is accomplished when the chip enable (/CE) and write enable(/WE) inputs are both LOW.

Data on the input/output pins (DQ0 through DQ23) of the device is written into the memory location specified on the address pins (A0 through A14).

Reading the device is accomplished by taking the chip enable (/CE) and output enable(/OE) LOW while write enable(/WE) remains HIGH. Under these conditions, the contents of the memory location specified on the address pins will appear on the input/output pins.

The input/output pins remains in a high-impedance state unless the module is selected, outputs are enabled, and write enable is HIGH.

FEATURES

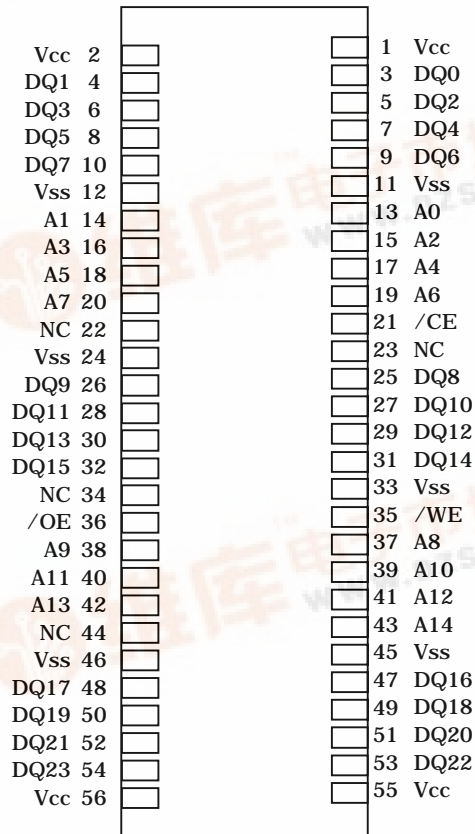
- ◆ Access times : 12, 15 and 20ns
- ◆ High-density 768Kbit design
- ◆ High-reliability, high-speed design
- ◆ Single + 5V ±0.5V power supply
- ◆ 56-pin, low-active power design
- ◆ All inputs and outputs are TTL-compatible
- ◆ Industry-standard pinout
- ◆ FR4-PCB design
- ◆ Part identification

HMS3224M3 : 56Pin SIMM Design

HMS3224Z3 : 56Pin ZIP Design

→Pin-compatible with the HMS3224M3

PIN ASSIGNMENT



**ZIP
TOP VIEW**

OPTIONS

- ◆ Timing

| | |
|-------------|-----|
| 12ns access | -12 |
| 15ns access | -15 |
| 20ns access | -20 |

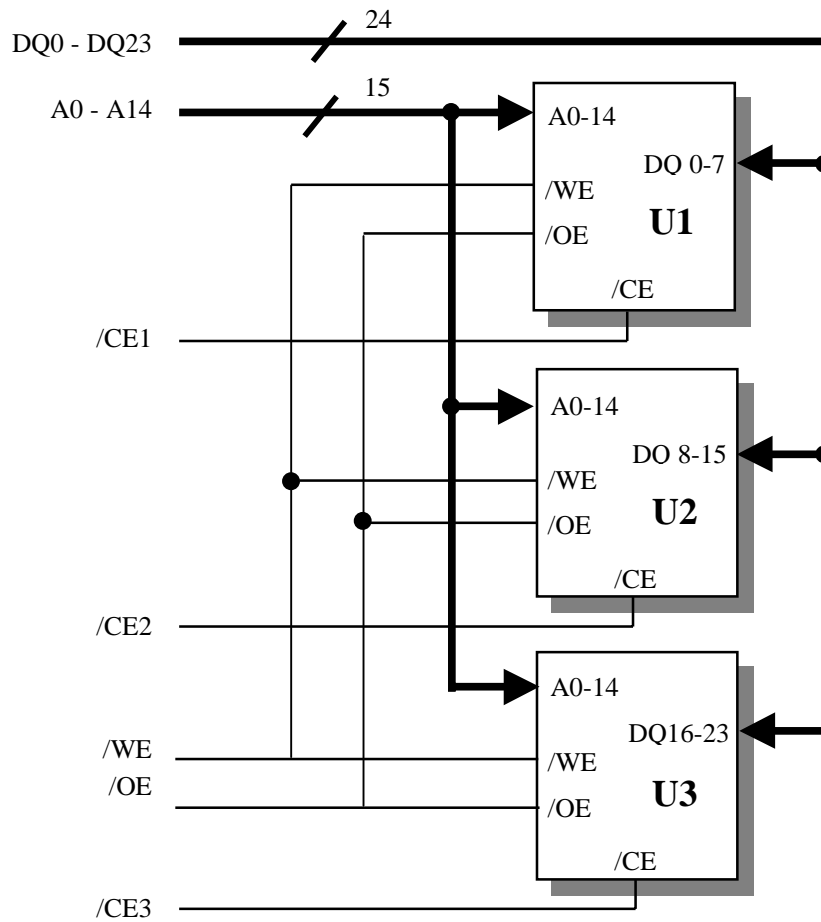
- ◆ Packages

| | |
|-------------|---|
| 56-pin SIMM | M |
| 56-pin ZIP | Z |

MARKING



FUNCTIONAL BLOCK DIAGRAM



TRUTH TABLE

| MODE | /OE | /CE | /WE | OUTPUT | POWER |
|--------------|-----|-----|-----|--------|---------|
| STANDBY | X | H | X | HIGH-Z | STANDBY |
| NOT SELECTED | H | L | H | HIGH-Z | ACTIVE |
| READ | L | L | H | Dout | ACTIVE |
| WRITE | X | L | L | Din | ACTIVE |

ABSOLUTE MAXIMUM RATINGS

| PARAMETER | SYMBOL | RATING |
|---|---------------------|-----------------|
| Voltage on Any Pin Relative to V _{SS} | V _{IN,OUT} | -0.5V to +7.0V |
| Voltage on V _{CC} Supply Relative to V _{SS} | V _{CC} | -0.5V to +7.0V |
| Power Dissipation | P _D | 3W |
| Storage Temperature | T _{STG} | -65°C to +150°C |
| Operating Temperature | T _A | 0°C to +70°C |

- Stresses greater than those listed under " Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operating section of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

RECOMMENDED DC OPERATING CONDITIONS (T_A=0 to 70 °C)

| PARAMETER | SYMBOL | MIN | TYP. | MAX |
|--------------------|-----------------|-------|------|-------------------------|
| Supply Voltage | V _{CC} | 4.5V | 5.0V | 5.5V |
| Ground | V _{SS} | 0 | 0 | 0 |
| Input High Voltage | V _{IH} | 2.2 | - | V _{CC} +0.5V** |
| Input Low Voltage | V _{IL} | -0.5* | - | 0.8V |

* V_{IL}(Min.) = -2.0V (Pulse Width ≤ 10ns) for I ≤ 20 mA

** V_{IH}(Min.) = V_{CC}+2.0V (Pulse Width ≤ 10ns) for I ≤ 20 mA

DC AND OPERATING CHARACTERISTICS (1)(0°C ≤ T_A ≤ 70 °C ; V_{CC} = 5V ± 0.5V)

| PARAMETER | TEST CONDITIONS | SYMBOL | MIN | MAX | UNITS |
|------------------------|--|-----------------|-----|-----|-------|
| Input Leakage Current | V _{IN} = V _{SS} to V _{CC} | I _{L1} | -6 | 6 | μA |
| Output Leakage Current | $\overline{CE}=V_{IH}$ or $\overline{OE}=V_{IH}$ or $\overline{WE}=V_{IL}$ V _{OUT} =V _{SS} to V _{CC} | I _{L0} | -6 | 6 | μA |
| Output High Voltage | I _{OH} = -4.0mA | V _{OH} | 2.4 | | V |
| Output Low Voltage | I _{OL} = 8.0mA | V _{OL} | | 0.4 | V |

* V_{CC}=5.0V, Temp=25 °C

DC AND OPERATING CHARACTERISTICS (2)

| DESCRIPTION | TEST CONDITIONS | SYMBOL | MAX | | | UNIT |
|---------------------------------|---|------------------|-----|-----|-----|------|
| | | | -12 | -15 | -20 | |
| Power Supply Current: Operating | Min. Cycle, 100% Duty /CE=V _{IL} , V _{IN} =V _{IH} or V _{IL} , I _{OUT} =0mA | I _{CC} | 495 | 450 | 420 | mA |
| Power Supply Current :Standby | Min. Cycle, /CE=V _{IH} | I _{SB} | 120 | 120 | 120 | mA |
| | f=0MHZ, /CE≥V _{CC} -0.2V, V _{IN} ≥ V _{CC} -0.2V or V _{IN} ≤0.2V | I _{SB1} | 6 | 6 | 6 | mA |

CAPACITANCE

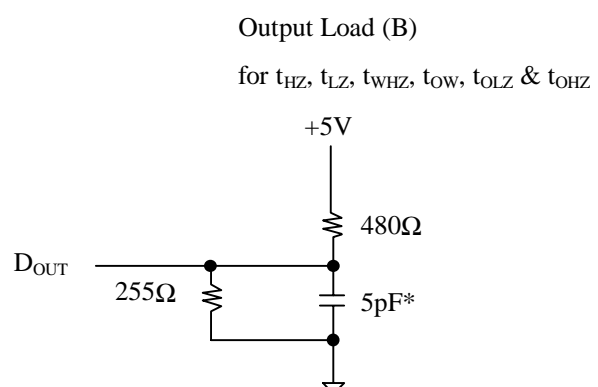
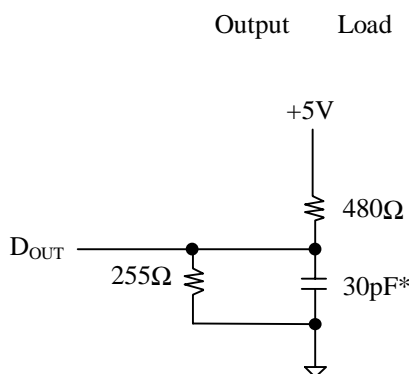
| DESCRIPTION | TEST CONDITIONS | SYMBOL | MAX | UNIT |
|---------------------------|---------------------|-----------------|-----|------|
| Input /Output Capacitance | V _{IO} =0V | C _{IO} | 24 | pF |
| Input Capacitance | V _{IN} =0V | C _{IN} | 21 | pF |

* NOTE : Capacitance is sampled and not 100% tested

AC CHARACTERISTICS (0°C ≤ T_A ≤ 70 °C ; V_{CC} = 5V ± 0.5V, unless otherwise specified)

TEST CONDITIONS

| PARAMETER | VALUE |
|--|-----------|
| Input Pulse Level | 0 to 3V |
| Input Rise and Fall Time | 3ns |
| Input and Output Timing Reference Levels | 1.5V |
| Output Load | See below |



READ CYCLE

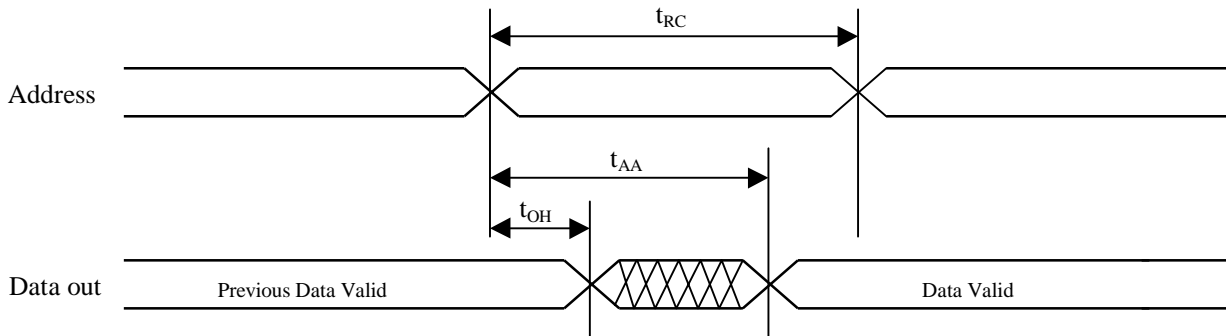
| PARAMETER | SYMBOL | -12 | | -15 | | -20 | | UNIT |
|---------------------------------|-----------|-----|-----|-----|-----|-----|-----|------|
| | | MIN | MAX | MIN | MAX | MIN | MAX | |
| Read Cycle Time | t_{RC} | 12 | | 15 | | 20 | | ns |
| Address Access Time | t_{AA} | | 12 | | 15 | | 20 | ns |
| Chip Select to Output | t_{CO} | | 12 | | 15 | | 20 | ns |
| Output Enable to Output | t_{OE} | | 6 | | 7 | | 9 | ns |
| Output Enable to Low-Z Output | t_{OLZ} | 0 | | 0 | | 0 | | ns |
| Chip Enable to Low-Z Output | t_{LZ} | 3 | | 3 | | 3 | | ns |
| Output Disable to High-Z Output | t_{OHZ} | 0 | 6 | 0 | 7 | 0 | 10 | ns |
| Chip Disable to High-Z Output | t_{HZ} | 0 | 6 | 0 | 7 | 0 | 10 | ns |
| Output Hold from Address Change | t_{OH} | 3 | | 3 | | 3 | | ns |
| Chip Select to Power Up Time | t_{PU} | 0 | | 0 | | 0 | | ns |
| Chip Select to Power Down Time | t_{PD} | | 12 | | 15 | | 20 | ns |

WRITE CYCLE

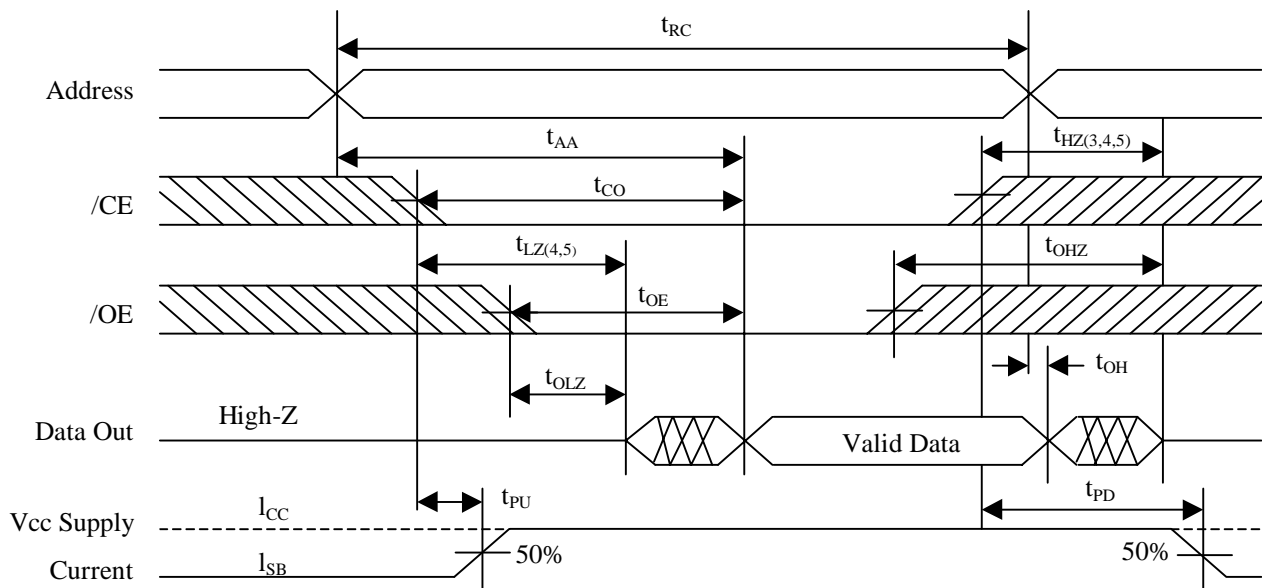
| PARAMETER | SYMBOL | -12 | | -15 | | -20 | | UNIT |
|-------------------------------|-----------|-----|-----|-----|-----|-----|-----|------|
| | | MIN | MAX | MIN | MAX | MIN | MAX | |
| Write Cycle Time | t_{WC} | 12 | | 15 | | 20 | | ns |
| Chip Select to End of Write | t_{CW} | 9 | | 11 | | 13 | | ns |
| Address Set-up Time | t_{AS} | 0 | | 0 | | 0 | | ns |
| Address Valid to End of Write | t_{AW} | 9 | | 12 | | 13 | | ns |
| Write Pulse Width | t_{WP} | 9 | | 12 | | 13 | | ns |
| Write Recovery Time | t_{WR} | 12 | | 0 | | 0 | | ns |
| Write to Output High-Z | t_{WHZ} | 0 | 6 | 0 | 8 | 0 | 8 | ns |
| Data to Write Time Overlap | t_{DW} | 7 | | 8 | | 10 | | ns |
| Data Hold from Write Time | t_{DH} | 0 | | 0 | | 0 | | ns |
| End of Write to Output Low-Z | t_{OW} | 0 | | 0 | | 0 | | ns |

TIMING DIAGRAMS

TIMING WAVEFORM OF READ CYCLE(Address Controlled) (/CE =/OE = V_{IL} , /WE = V_{IH})



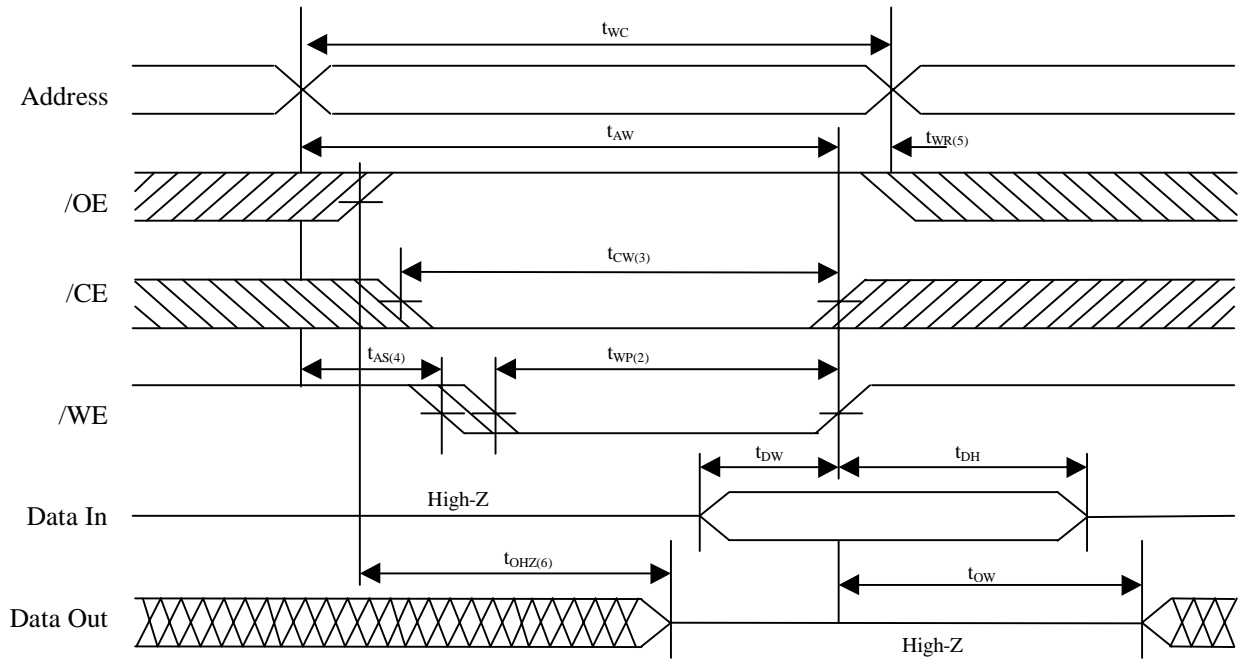
TIMING WAVEFORM OF READ CYCLE (/WE=V_{IH})



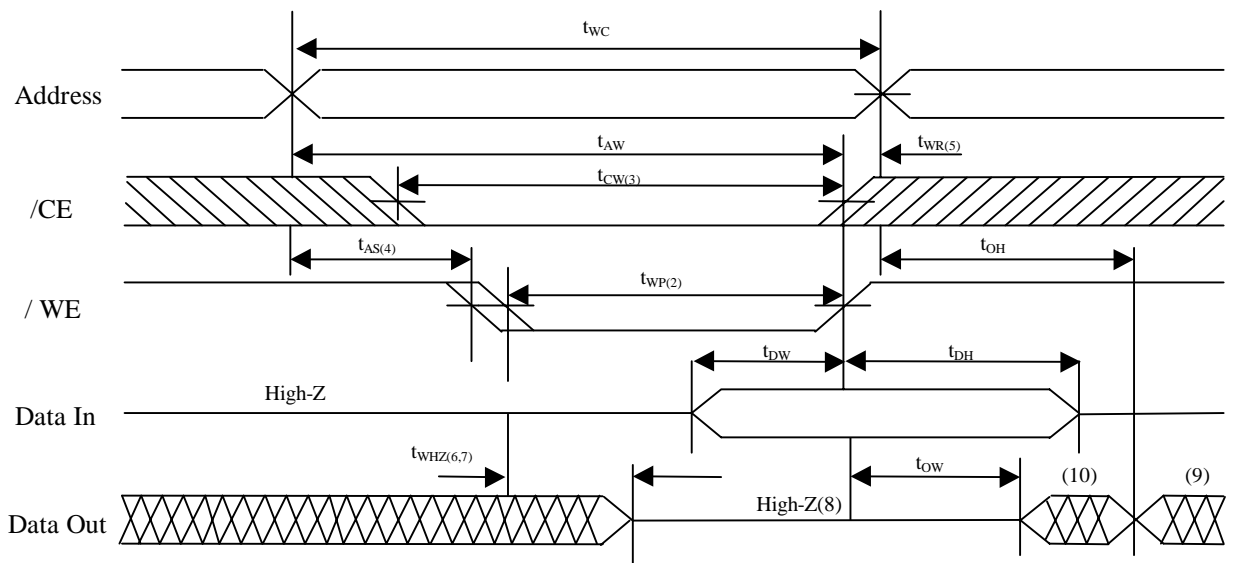
Notes (Read Cycle)

1. /WE is high for read cycle.
2. All read cycle timing is referenced from the last valid address to the first transition address.
3. t_{HZ} and t_{O_{HZ}} are defined as the time at which the outputs achieve the open circuit condition are not referenced to V_{OH} or V_{OL} levels.
4. At any given temperature and voltage condition, t_{HZ} (max.) is less than t_{LZ} (min.) both for a given device and from device to device.
5. Transition is measured ± 200mV from steady state voltage with Load (B). This parameter is sampled and not 100% tested.
6. Device is continuously selected with /CE = V_{IL}.
7. Address valid prior to coincident with /CE transition low.

TIMING WAVEFORM OF WRITE CYCLE (/OE = Clock)



TIMING WAVEFORM OF WRITE CYCLE (/OE Low Fixed)



Notes(Write Cycle)

1. All write cycle timing is referenced from the last valid address to the first transition address.
2. A write occurs during the overlap of a low /CE and a low /WE. A write begins at the latest transition among /CE going low and /WE going low: A write ends at the earliest transition among /CE going high and /WE going high. t_{WP} is measured from the beginning of write to the end of write.

3. t_{CW} is measured from the later of /CE going low to the end of write.
4. t_{AS} is measured from the address valid to the beginning of write.
5. t_{WR} is measured from the end of write to the address change. t_{WR} applied in case a write ends as /CE, or /WE going high.
6. If /OE,/CE and /WE are in the read mode during this period, the I/O pins are in the output low-Z state. Inputs of opposite phase of the output must not be applied because bus contention can occur.
7. For common I/O applications, minimization or elimination of bus contention conditions is necessary during read and write cycle.
8. If /CE goes low simultaneously with /WE going low or after /WE going low, the outputs remain high impedance state.
9. D_{OUT} is the read data of the new address.
10. When /CE is low: I/O pins are in the output state. The input signals in the opposite phase leading to the output should not be applied.

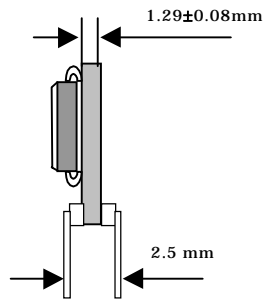
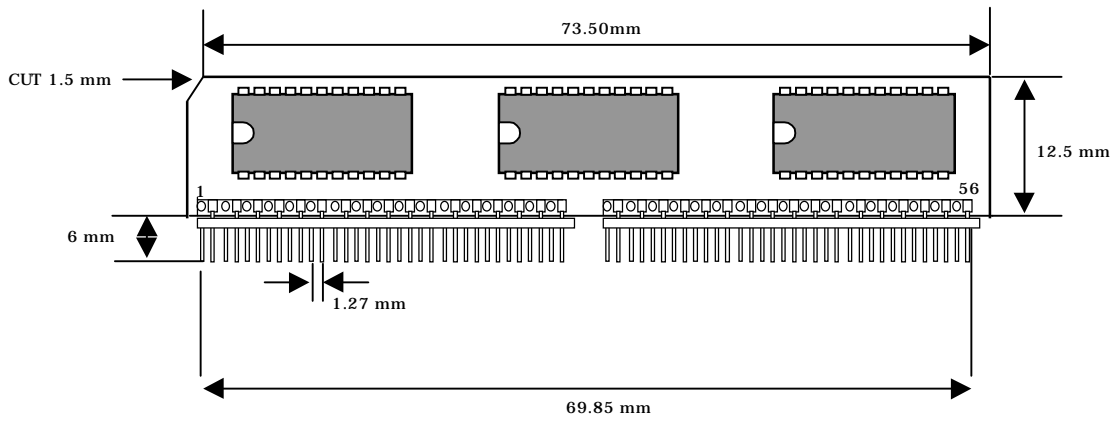
FUNCTIONAL DESCRIPTION

| /CE | /WE | /OE | MODE | I/O PIN | SUPPLY CURRENT |
|-----|-----|-----|----------------|-----------|-------------------|
| H | X* | X | Not Select | High-Z | I_{SB}, I_{SB1} |
| L | H | H | Output Disable | High-Z | I_{CC} |
| L | H | L | Read | D_{OUT} | I_{CC} |
| L | L | X | Write | D_{IN} | I_{CC} |

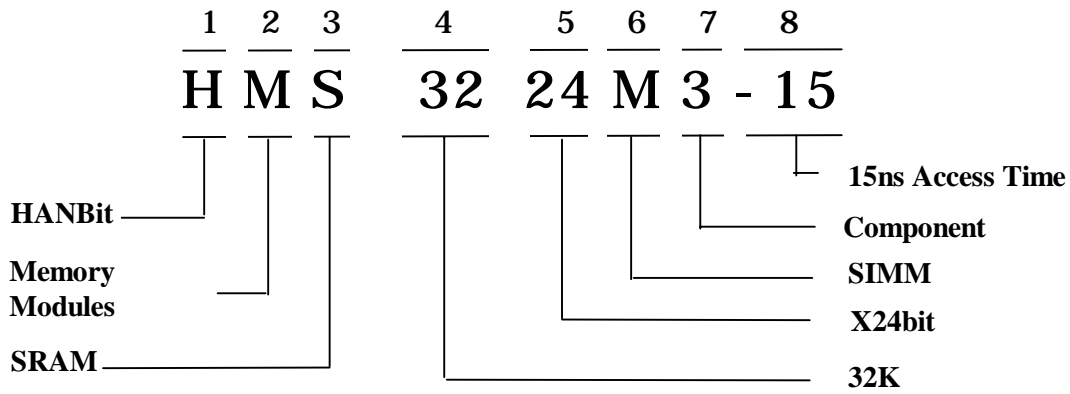
Note: X means Don't Care

PACKAGING INFORMATION

ZIP Design



ODERING INFORMATION



1. - Product Line Identifier

HANBit Technology ----- **H**

2. - Memory Modules

3. - SRAM

4. - Depth : 32K

5. - Width : x 24bit

6. - Package Code

SIMM ----- **M**

ZIP ----- **Z**

7. - Number of Memory Components

8. - Access time

10 ----- 10ns

12 ----- 12ns

15 ----- 15ns

17 ----- 17ns

20 ----- 20ns